

MULTILAYERED CERAMIC BOARD, METHOD
FOR FABRICATING THE SAME, AND ELECTRONIC
DEVICE USING MULTILAYERED CERAMIC BOARD

ABSTRACT OF THE DISCLOSURE

A method for fabricating a multilayered ceramic board includes forming a green laminate, the green laminate including a plurality of green base layers containing a low-temperature sinterable ceramic material which is a ceramic powder and a glass component, and a binder; at least one green constraining layer disposed in contact with a principal surface of a specific green base layer, the green constraining layer containing an inorganic material powder which is not sintered at the sintering temperature of the low-temperature sinterable ceramic material; and wiring conductors; and firing the green laminate at the sintering temperature of the low-temperature sinterable ceramic material. The firing step includes a binder removal step and a sintering step for obtaining the sintered state of the low-temperature sinterable ceramic material in which the ceramic powder is densified while the glass component is fluidized. The rate of temperature increase from the binder removal step to the sintering step is set to be more than about 20°C/minute.